



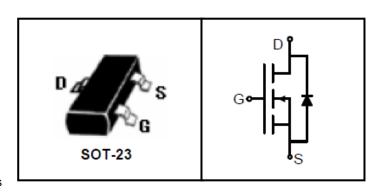
20V N-Channel Trench MOSFET

FEATURES

- Trench Power MOSFET Technology
- Low R_{DS(ON)}
- Low Gate Charge
- Optimized For Fast-switching Applications

APPLICATIONS

- Synchronous Rectification in DC/DC and AC/DC Converters
- Isolated DC/DC Converters in Telecom and Industrial





Device Marking and Package Information				
Device	Package	Marking		
TTX2302	SOT-23	2302		

Absolute Maximum Ratings $T_C = 25^{\circ}C$, unless otherwise noted						
Devementer	Cumbal	Value				
Parameter	Symbol	SOT-23	- Unit			
Drain-Source Voltage (V _{GS} = 0V)	V _{DSS}	20	V			
Continuous Drain Current	I _D	4	А			
Pulsed Drain Current (note1)	I _{DM}	16	Α			
Gate-Source Voltage	V_{GSS}	±10	V			
Single Pulse Avalanche Energy (note2)	E _{AS}	7.4	mJ			
Avalanche Current	I _{AS}	7	Α			
Power Dissipation (T _C = 25°C)	P_{D}	1	W			
Operating Junction and Storage Temperature Range	T_J,T_stg	-55~+150	°C			

Thermal Resistance					
Parameter	Sumb al	Value	- Unit		
Parameter	Symbol	SOT-23			
Thermal Resistance, Junction-to-Case	R _{thJC}	14.4	00/14/		
Thermal Resistance, Junction-to-Ambient	R _{thJA}	125	°C/W		



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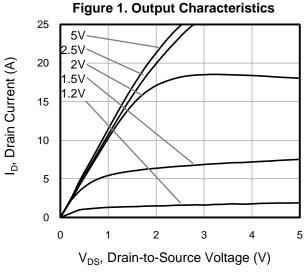
Specifications $T_J = 25^{\circ}C$, ur	iless othe	rwise noted					
Parameter	Symbol	Test Conditions	Value			Unit	
			Min.	Тур.	Max.		
Static							
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS} = 0V, I_{D} = 250\mu A$	20			V	
7. 0 () / ()		$V_{DS} = 20V, V_{GS} = 0V, T_{J} = 25^{\circ}C$	1		1		
Zero Gate Voltage Drain Current	I _{DSS}	$V_{DS} = 20V, V_{GS} = 0V, T_{J} = 150^{\circ}C$			100	μΑ	
Gate-Source Leakage	I_{GSS}	$V_{GS} = \pm 10V$			±100	nA	
Gate-Source Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	0.5	0.7	1.2	V	
		$V_{GS} = 10V, I_{D} = 2A$		18.5	23.5	mΩ	
Drain-Source On-Resistance (Note3)	R _{DS(on)}	$V_{GS} = 4.5V, I_{D} = 2A$		21.5	27.5	mΩ	
		$V_{GS} = 2.5V, I_{D} = 2A$		28	36.5	mΩ	
Forward Transconductance (Note3)	g _{fs}	$V_{DS} = 5V$, $I_D = 2A$		8		S	
Dynamic							
Input Capacitance	C _{iss}	V - 0V		621		pF	
Output Capacitance	C _{oss}	$V_{GS} = 0V,$ $V_{DS} = 10V,$		135			
Reverse Transfer Capacitance	C _{rss}	f = 1.0MHz		58			
Tetal Octo Ohanna	Q _g (10V)			12			
Total Gate Charge	Q _g (4.5V)	$V_{DD} = 10V, I_D = 4A,$		5.8			
Gate-Source Charge	Q_{gs}	$V_{DD} = 10V, I_D = 4A,$ $V_{GS} = 10V$		0.7		nC	
Gate-Drain Charge	Q_{gd}			1.8			
Turn-on Delay Time	t _{d(on)}			15			
Turn-on Rise Time	t _r	$V_{DD} = 10V, I_D = 4A,$		17		ns	
Turn-off Delay Time	t _{d(off)}	$R_G = 2.5\Omega$		42			
Turn-off Fall Time	t _f			40			
Drain-Source Body Diode Characteri	stics		-	-	-		
Continuous Body Diode Current	I _s	T 0500			4		
Pulsed Diode Forward Current	I _{SM}	$T_{C} = 25^{\circ}C$			16	A	
Body Diode Voltage	V _{SD}	$T_J = 25^{\circ}C$, $I_{SD} = 4A$, $V_{GS} = 0V$			1.2	V	

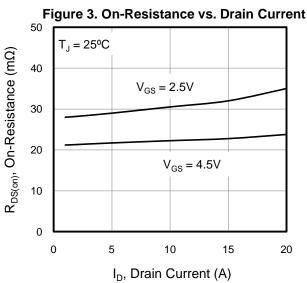
Notes

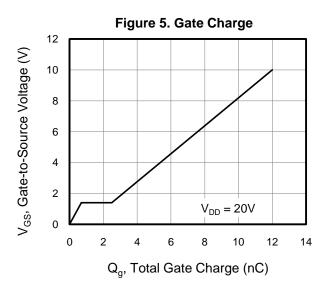
- 1. Repetitive Rating: Pulse Width limited by maximum junction temperature
- 2. V_{DD} = 20V, R_G = 25 Ω , Starting T_J = 25 $^{\circ}$ C
- 3. Pulse Test: Pulse Width ≤ 300µs, Duty Cycle ≤ 1%

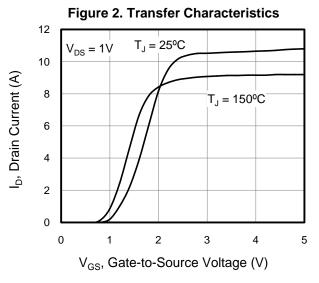


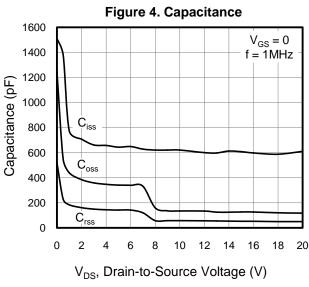
Typical Characteristics $T_J = 25^{\circ}\text{C}$, unless otherwise noted

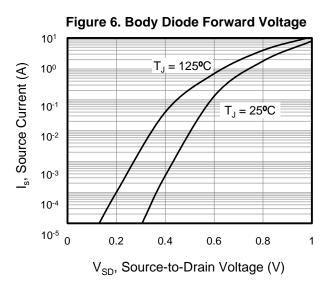






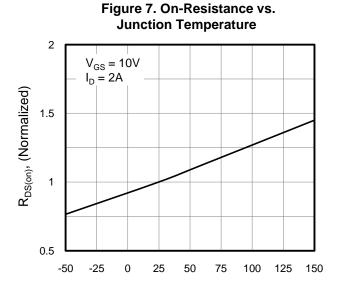








Typical Characteristics $T_J = 25^{\circ}C$, unless otherwise noted



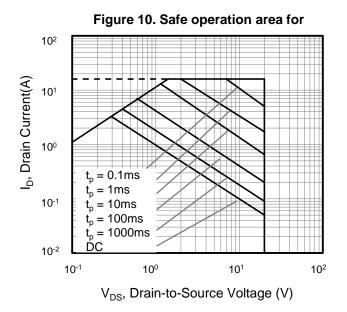
T_{.,}, Junction Temperature (°C)

Figure 8. Threshold Voltage vs. Junction Temperature

0.4

0.2 $0.2 \\ 0.2 \\ 0.2 \\ 0.2 \\ 0.2 \\ 0.2 \\ 0.3 \\ 0.4 \\ 0.5 \\ 0.4 \\ 0.5 \\ 0.4 \\ 0.5 \\ 0.5 \\ 0.25 \\$

Figure 9. Transient Thermal Impedance 10¹ Z_{thJC}, Thermal Impedance (Normalized) 100 D = 0.510-1 D = 0.2D = 0.1D = 0.0510-2 D = 0.02D = 0.01Single Pulse 10-3 10-4 10-6 10-5 10⁻³ 10-2 10-1 T_p, Pulse Width (s)



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Figure A: Gate Charge Test Circuit and Waveform

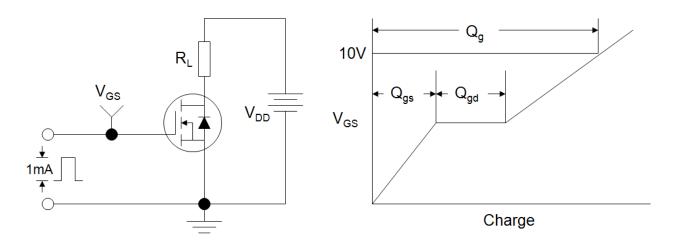


Figure B: Resistive Switching Test Circuit and Waveform

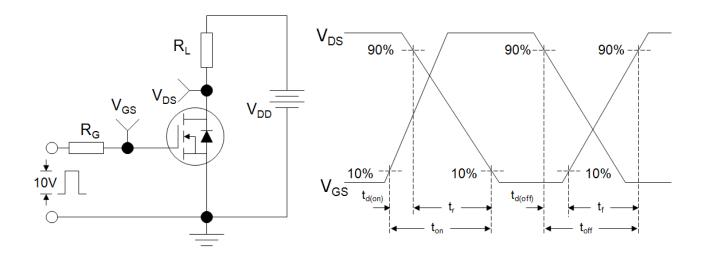
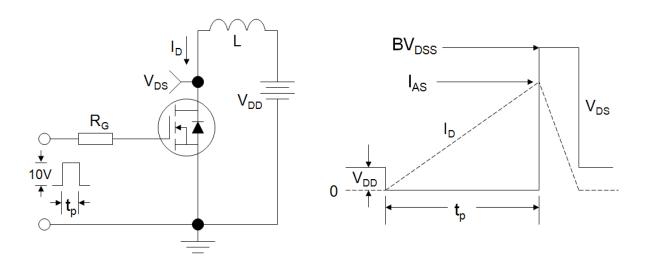
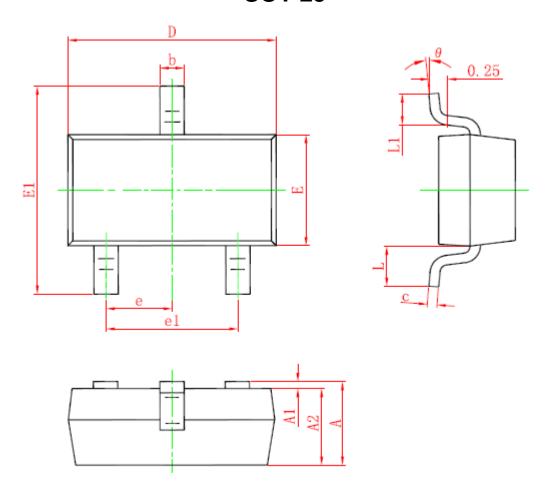


Figure C: Unclamped Inductive Switching Test Circuit and Waveform





SOT-23



Cumbal	Dimensions In Millimeters		Dimensions In Inches		
Symbol	Min.	Max.	Min.	Max.	
Α	0.900	1.150	0.035	0.045	
A1	0.000	0.100	0.000	0.004	
A2	0.900	1.050	0.035	0.041	
b	0.300	0.500	0.012	0.020	
С	0.080	0.150	0.003	0.006	
D	2.800	3.000	0.110	0.118	
E	1.200	1.400	0.047	0.055	
E1	2.250	2.550	0.089	0.100	
е	0.950 TYP.		0.037 TYP.		
e1	1.800	2.000	0.071	0.079	
L	0.550 REF.		0.022 REF.		
L1	0.300	0.500	0.012	0.020	
θ	0°	8°	0°	8°	



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